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**Field device tool (FDT) interface specification –  
Part 303-1: Communication profile integration – IEC 61784 CP 3/1 and CP 3/2**

**Spécification des interfaces des outils des dispositifs de terrain (FDT) –  
Partie 303-1: Intégration des profils de communication – IEC 61784 CP 3/1  
et CP 3/2**



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**FIELD DEVICE TOOL (FDT) INTERFACE SPECIFICATION –**

**Part 303-1: Communication profile integration –  
IEC 61784 CP 3/1 and CP 3/2**

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**This Consolidated version of IEC 62453-303-1 bears the edition number 1.1. It consists of the first edition (2009-06) [documents 65E/127/FDIS and 65E/140/RVD] and its amendment 1 (2016-06) [documents 65E/336/CDV and 65E/395A/RVC]. The technical content is identical to the base edition and its amendment.**

**In this Redline version, a vertical line in the margin shows where the technical content is modified by amendment 1. Additions are in green text, deletions are in strikethrough red text. A separate Final version with all changes accepted is available in this publication.**

International Standard IEC 62453-303-1 been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

Each part of the IEC 62453-3xy series is intended to be read in conjunction with IEC 62453-2.

The French version of this standard has not been voted upon.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 62453 series, under the general title *Field Device Tool (FDT) interface specification*, can be found on the IEC website.

The committee has decided that the contents of the base publication and its amendment will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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## INTRODUCTION

This part of IEC 62453 is an interface specification for developers of FDT (Field Device Tool) components for function control and data access within a client/server architecture. The specification is a result of an analysis and design process to develop standard interfaces to facilitate the development of servers and clients by multiple vendors that need to interoperate seamlessly.

With the integration of fieldbuses into control systems, there are a few other tasks which need to be performed. In addition to fieldbus- and device-specific tools, there is a need to integrate these tools into higher-level system-wide planning- or engineering tools. In particular, for use in extensive and heterogeneous control systems, typically in the area of the process industry, the unambiguous definition of engineering interfaces that are easy to use for all those involved is of great importance.

A device-specific software component, called DTM (Device Type Manager), is supplied by the field device manufacturer with its device. The DTM is integrated into engineering tools via the FDT interfaces defined in this specification. The approach to integration is in general open for all kinds of fieldbuses and thus meets the requirements for integrating different kinds of devices into heterogeneous control systems.

Figure 1 shows how IEC 62453–303-1 is aligned in the structure of the IEC 62453 series.

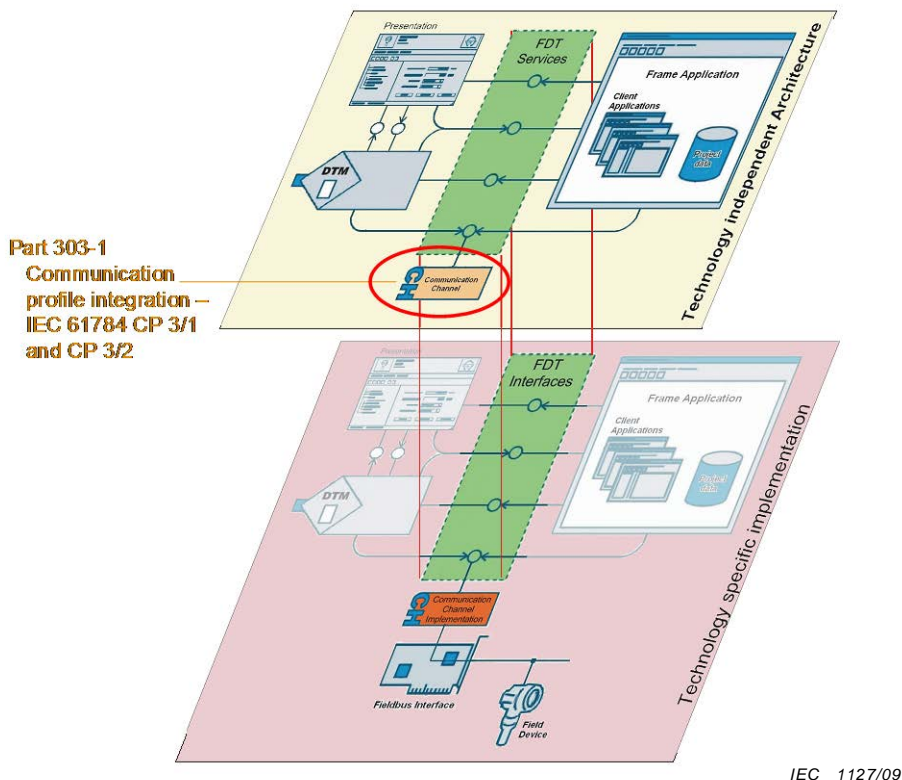


Figure 1 – Part 303-1 of the IEC 62453 series

## FIELD DEVICE TOOL (FDT) INTERFACE SPECIFICATION –

### Part 303-1: Communication profile integration – IEC 61784 CP 3/1 and CP 3/2

#### 1 Scope

Communication Profile 3/1 and Communication Profile 3/2 (commonly known as PROFIBUS™<sup>1</sup>) defines communication profiles based on IEC 61158-2 Type 3, IEC 61158-3-3, IEC 61158-4-3, IEC 61158-5-3, and IEC 61158-6-3. The basic profiles CP 3/1 (PROFIBUS DP) and CP 3/2 (PROFIBUS PA) are defined in IEC 61784-1.

This part of IEC 62453 provides information for integrating the PROFIBUS protocol into the FDT interface specification (IEC 62453–2).

This part of the IEC 62453 specifies communication and other services.

This specification neither contains the FDT specification nor modifies it.

#### 2 Normative references

The following referenced documents are indispensable for the application of this specification. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies

IEC 61131-3:2003, *Programmable controllers – Part 3: Programming languages*

IEC 61158 (all parts), *Industrial communication networks – Fieldbus specifications*

IEC 61158-2:2014, *Industrial communication networks – Fieldbus specifications – Part 2: Physical layer specification and service definition*

IEC 61158-3-3, *Industrial communication networks – Fieldbus specifications – Part 3-3: Data-link layer service definition – Type 3 elements*

IEC 61158-4-3 *Industrial communication networks – Fieldbus specifications – Part 4-3: Data-link layer protocol specification – Type 3 elements*

IEC 61158-5-3: *Industrial communication networks – Fieldbus specifications – Part 5-3: Application layer service definition – Type 3 elements*

IEC 61158-6-3, *Industrial communication networks – Fieldbus specifications – Part 6-3: Application layer protocol specification – Type 3 elements*

IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus profiles*

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